IN THE CLAIMS:

1. (Previously Presented) A multi-zoned processing pad assembly for processing a substrate, comprising:

a conductive layer;

an upper layer having a non-conductive processing surface coupled to the conductive layer;

a conductive surface positioned substantially coplanar with the non-conductive processing surface, wherein a side of the substrate disposed on the upper layer contacts the conductive and non-conductive processing surface; and

at least two zones of different current permeability defined across the processing surface of the upper layer, wherein the at least two zones are defined by an attribute of the upper layer.

2. (Original) The assembly of claim 1, further comprising at least one aperture formed through the upper layer and the conductive layer.

3. (Original) The assembly of claim 1, wherein the at least two zones are formed via at least two sets of a plurality of holes in at least the upper layer, wherein the holes in each set of holes have substantially equal spacing but different diameters.

4. (Original) The assembly of claim 1, wherein the at least two zones are formed via at least two sets of a plurality of holes in at least the upper layer, wherein the holes in each set of holes have substantially equal diameters but different spacing.

5. (Original) The assembly of claim 1, wherein the at least two zones are formed via at least two sets of a plurality of holes in at least the upper layer, wherein the holes in each set of holes have different diameters and different spacing.

6. (Original) The assembly of claim 1, wherein the upper layer is fabricated of a permeable material, and wherein the at least two zones is defined by portions of the upper layer having different permeability.

7. (Original) The assembly of claim 1, wherein the upper layer further comprises:
a first ring of permeable material; and
at least a second ring of permeable material coupled to the first ring, wherein the first and second rings of permeable material have different porosity.

8. (Original) The assembly of claim 1, further comprising a subpad disposed between the upper layer and the conductive layer.

9. (Original) The assembly of claim 1, wherein the conductive layer further comprises a plurality of independently biasable electrical zones.

10. (Original) The assembly of claim 1, wherein the at least two zones further comprises a first zone having a greater open area than a second zone.

11. (Original) The assembly of claim 1, wherein the at least two zones further comprises a first zone adapted to allow a greater volume of electrolyte therethrough relative to a second zone.

12. (Previously Presented) The assembly of claim 1, further comprising:
a terminal disposed to the conductive layer for coupling to a power source, and
a subpad coupled to the conductive layer.

13. (Original) The assembly of claim 12, further comprising at least one aperture formed through the upper layer, the subpad, and the conductive layer.

14. (Previously Presented) The assembly of claim 1, wherein the conductive surface is coupled to a power source.

15. (Original) The assembly of claim 14, wherein the plurality of independently biasable electrical zones further comprises three independently biasable electrical zones formed by the interaction between a first conductive element and a second conductive element disposed in the conductive layer, wherein the second conductive element has an inner edge interleaved with an outer edge of the first conductive element.

16. (Original) The assembly of claim 15, wherein the at least two zones further comprises three zones aligned above the three electrical zones.

17-25. (Cancelled)

26. (Previously Presented) The assembly of claim 1, wherein the contact assembly is configured to bias a substrate during processing.

27. (Previously Presented) The assembly of claim 1, wherein electrolyte is supplied to the upper layer through the contact assembly.

28-29. (Cancelled)